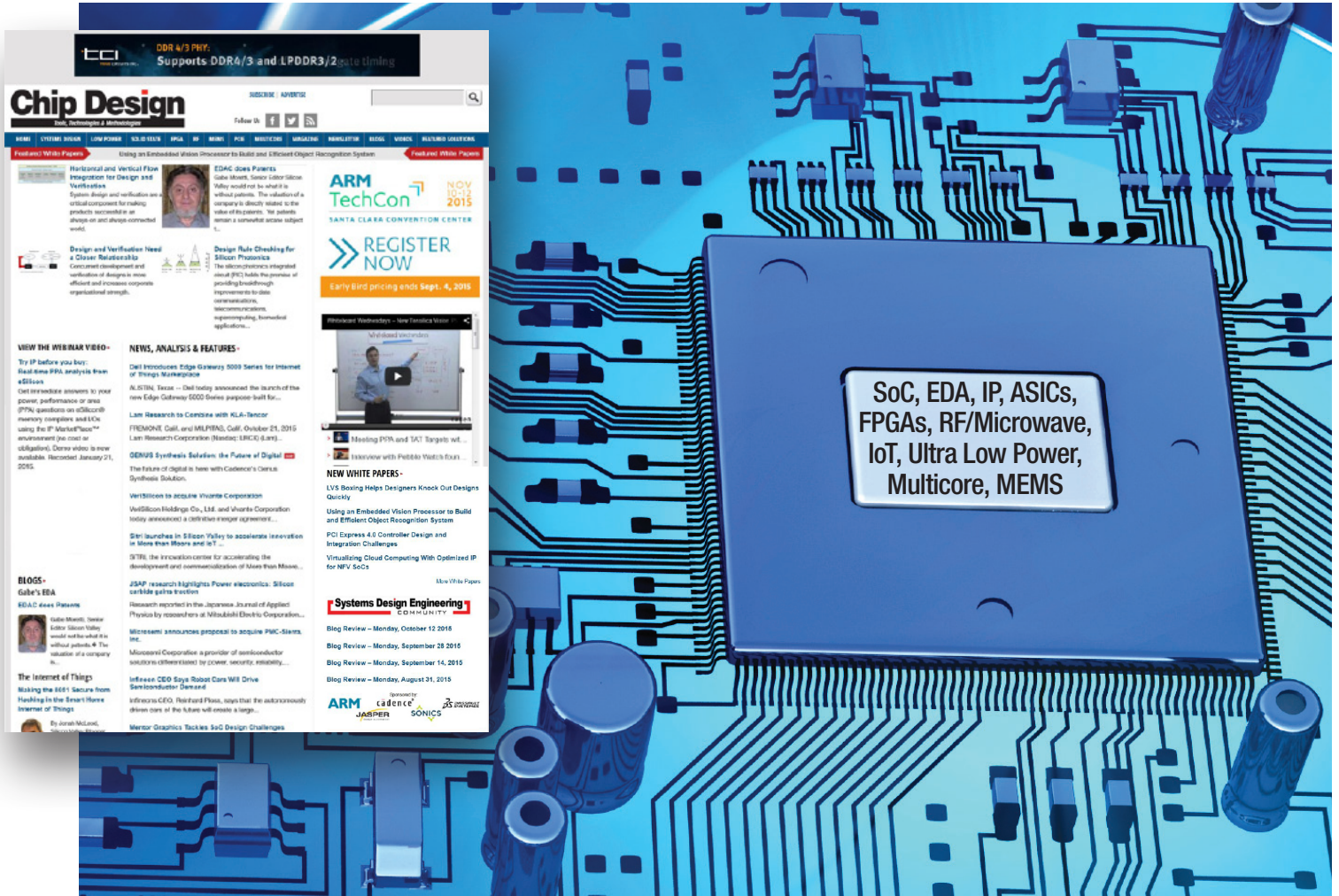# Chip Design

Tools, Technologies & Methodologies

Chip Design Marketing and Lead Generation Programs Connect You with Real Buyers in the Advanced IC Design Market

SoC, EDA, IP, ASICs, FPGAs, RF/Microwave, IoT, Ultra Low Power, Multicore, MEMS

Online Marketing. Surveys. Editorial Sponsorships. Newsletters. Magazine. Product Marketing. Lead Generation. Conference. White Papers. Email Blasts.

Affiliate Sponsor Support: accellera · EDA CONSORTIUM · GSA · INTERNATIONAL ENGINEERING CONSORTIUM · OCP International Partnership · Si2 Silicon Integration Initiative, Inc.

Informing Chip and SoC design decision makers with unparalleled technology and business insights

Chip Design's in-depth magazine, convenient email newsletters and content-rich websites are seen by **more than 120,000 engineering and management professionals in 101 countries** each month. These influential professionals rely on *Chip Design* for SoC design, EDA, ASICs, IP, FPGAs, RF, and Low Power design articles and product information.

Chip Design ensures our content and your message reach buyers worldwide in the formats they prefer, including:

- **www.ChipDesignMag.com:** Purchase influencers research suppliers and products online using the Chip Design portal's informative articles, video library, news, research, white papers, and featured solutions guide.

- **Premium Content Channel:** System Design Engineering. Our editors create valuable content featuring our sponsors and their technology and deliver it to their target audience.

- **Magazine:** Our qualified audience of buyers is the largest and most diverse served by any Chip Design-focused magazine. They rely on our leading-edge and strategic articles and commentary to help make EDA; ASICs, FPGAs and PLD Design; IP and test development tools and equipment technology decisions.

- **Email Newsletters:** Design engineers and engineering managers working on advanced SoC designs stay informed by reading *Chip Designer* and *IP Designer & Integrator* for important industry news, product information, research, videos and more.

- **Events:** Semiconductor design and manufacturing industry leaders gather each year at *The Confab* to connect, collaborate and create the future. Executives and Engineers involved in the Multicore and IoT industries gather each year at the *Multicore DevCon* and *Internet of Things Developers Conference*.

Audience Demographics

System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about $4 billion.

Circulation by Job Responsibility

53.4% Engineering
27.9% Engineering Management
13.3% Executive & other Management
5.4% Other (R&D etc.)

Circulation breakdown by Purchasing Responsibility

94.8% — Specify/Authorize/Influence the purchase of Design Automation tools and software

80.6% — Specify/Authorize/Influence the purchase of ASICs, FPGAs and PLDs

70.1% — Specify/Authorize/Influence the purchase of Intellectual Property

52.9% — Specify/Authorize/Influence the purchase of Standard ICs Services

57.2% — Specify/Authorize/Influence the purchase of Test Equipment/Development Tools

35.6% — Influence, specify or authorize the purchasing at companies with revenues of over $500 million.

Top 30 Subscribing Companies

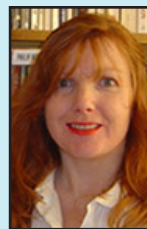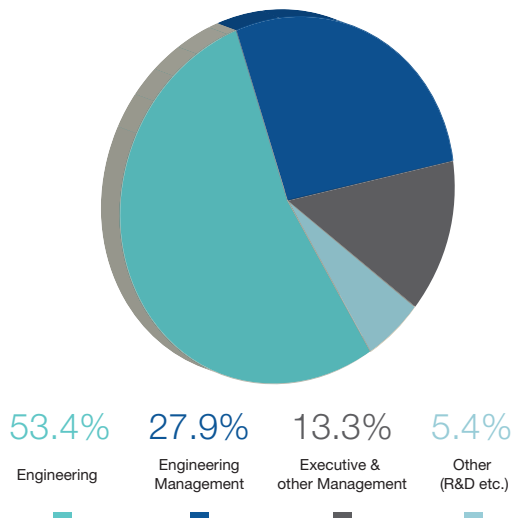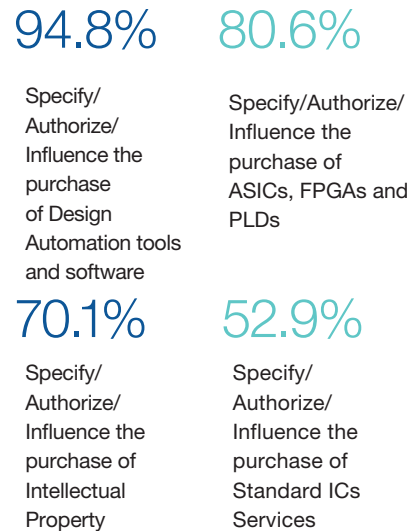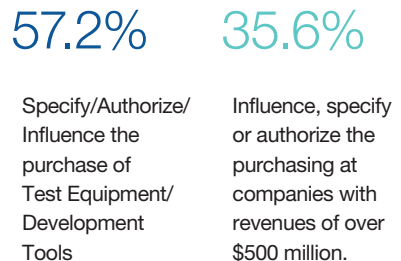|		
Altera	IBM	ON Semiconductor
AMD	IDT	Oracle
Analog Devices	Infineon	PMC-Sierra
Atmel	Intel	Qualcomm
Broadcom	Hewlett-Packard	Rohm Semiconductor
Cypress Semiconductor	LSI	Samsung Electronics
Cisco	Marvell	ST Microelectronics
Freescale	Maxim Integrated	Texas Instruments
Fujitsu	NVIDIA	VIA Technologies
GLOBALFOUNDRIES	NXP Semiconductors	Xilinx

PETE SINGER, *Editorial Director & Associate Publisher*

Pete oversees the editorial operations of Chip Design, Solid State Technology and The ConFab. He has been involved in technical journalism for more than 30 years and has written over 150 articles on all aspects of semiconductor manufacturing and design industries.

GABE MORETI
Senior Editor

Gabe Moretti has been in EDA for over 40 years. The first 31 were spent in engineering activities, developing EDA tools and participating in IEEE standards making activities.

CAROLINE HAYES
Senior Editor

Caroline Hayes has been a journalist, covering the electronics sector for over 20 years. She has worked on many titles, most recently the pan-European magazine, EPN.

CHRIS CIUFO
Content Director

Chris is Content Director for embedded content for Embedded Systems Engineering, EECatalog, and Embedded Intel® Solutions. He has 30 years of embedded technology experience with degrees in electrical engineering and materials science.

Marketing & Lead Generation Programs Connect with Targets

▶ Online, Lead Generation, Dedicated Email Blasts & Product Marketing

▶ www.chipdesignmag.com www.eecatalog.com/sensors
www.eecatalog.com/fpga www.chipdesignmag.com/rfmw

"Spotlight On" Position
(limited to 2 companies)
High impact and above the fold
Price - $4,000 per month

Banners
- Leaderboard (728x90) - $100 cpm
- Large Rectangle (336x280) - $100 cpm
- Half Page(300x600) - $100 cpm
- Welcome Page (800x600) - $450 cpm
- Exclusive "Push Down" Banner - High Impact banner expands to a maximum of 970 x 418 and then retracts to 970 x 90

Video Showcase Program:
$1,000; $2,500 for editorial interview

▶ Generation Leads with Technology Paper Sponsorship
Featured on the Chip Design
site for 6 months as a PDF

- **$1,500** (online only)
- **$2,950** (includes online, magazine, and dedicated email blast to 25,000)
- Featured on Chip Design website for 6 months
- Registration form to collect downloaders' contact information.
- Featured in six issues of Chip Designer e-Newsletter & Monthly White Paper Resource Newsletter distributed to over 50,000 subscribers.

Dedicated Email Blasts
Generate powerful leads with Chip Design Dedicated Email Blasts
- $295 cpm
- 15,000 minimum list size

▶ Chip Design's Elite Marketing Membership
- Banner Impressions – 5,000 impressions each month (leaderboard or large rectangle)
- One Gold or Silver Sponsorship of *Chip Designer* or *IP Designer & Integrator* newsletter per quarter or an additional 2,000 banner impressions each month
- Posting of your message to our social media pages (nearly 4,000 Facebook and 1,000+ twitter follows and growing!)
- Unlimited press releases
- One online Product Showcase
- Feature 1 video or 1 white paper online
- 1 Dedicated email blast every 6 months – 15,000 (add-on)

Price: $950 per month – 6 month program
($1,350 per month/with email blast add-on/6 month program)

CHIPDESIGNMAG.COM	Avg. Monthly Page Views: 237,598	Page Visits: 42,053	Avg.Time on Site: 48:31

▶ Email Newsletters: Reach targeted audiences with Chip Design Email Newsletters

Chip Designer e-Newsletter (Bi-monthly): 45,000 Subscribers
IP Designer – Integrator e-Newsletter (Monthly): 33,000 Subscribers
RF & Microwave Systems e-newsletter (Quarterly): 30,000 Subscribers
FPGA & CPLD Quarterly Update e-newsletter: 36,000 Subscribers

Platinum Sponsor - Exclusive
468x90 banner at top center position and first text ad - $2,000/issue
Gold Sponsor - Exclusive
Skyscraper top right banner position and second text ad - $1,500/issue
Silver Sponsor - Exclusive
Second/third from top 125 x 125 banner position and third/fourth text ad - $1,000/issue

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▶ Market Surveys | Lead Generation

Each quarter in 2016, Chip Design will conduct a Market Intelligence Survey of its readership. Data collected includes industry trends, buying preferences, key factors influencing purchasing and evaluation decisions and much more including contact data on all respondents.
Custom surveys also available upon request

2016 Market Intelligence/Lead Generation Topics
IP Integration — February
RF/Microwave — April
EDA Tech & Tools — June
Verification — September
EDA Tech & Tools — November/December

Sponsorship net rate:
$3,950 (sponsor may add up to 3 proprietary questions at an additional fee of $2,500 per program)
Sign-up for all 4 surveys for $12,500

▶ Chip Design Magazine & Engineers' Guides focused on specific markets (FPGA's; RF and Microwave; Sensors & MEMs)

- Chip Design Magazine - 40,000 qualified subscribers
- Engineers' Guide to FPGA & PLD - 35,000 qualified subscribers
- Engineers' Guide to Sensors & MEMs - 40,000 qualified subscribers
- RF & Microwave Systems - 32,500 qualified subscribers

Bonus Distribution: DAC, DesignCon, ARMTechCon, DATE, DevCon, Semicon West, Embedded World, IoT DevCon, Embedded Systems Conference

Magazine Net Rate

Two-page Spread	$3,950
Full Page	$2,500
Half Page	$1,750
Back Cover	$4,000
Inside Back Cover	$3,500
Inside Front Cover Spread	$3,750
Page 1	$3,500

Product Showcase Rates

Full Page Product Showcase
$1,250
(additional products 50% off)

1/2 page Product Showcase
Net Rate: $950
(additional products 35% off)

▶ DVCon/DATE & DAC Special Offers

Magazine Incentives
Advertisers in the DVCon/Date and DAC show issues receive:
- **Resource Guide Product Showcase FREE in the Summer/Fall issue**

Video Showcase Program
- Promote a new product or announcement on camera at DAC
- Your video will be recorded at the event then posted on the Chip Design website and promoted in eight issues of Chip Designer to more than 40,000 SoC Designer decision makers
- PLUS, you receive a copy of the video to post on your site or YouTube and use for other marketing efforts
- Net rate $1,750; $2,500 for editorial interview

Product Showcase Newsletter - 35,000 Subscribers
Get exposure for your products, drive traffic to your booth and reach those unable to attend the show with a listing in the Product Showcase e-Newsletter.
- Product Listing: $750
- Leaderboard - $1,500 net
- Skyscraper on right rail - $1,500 net
- Silver (125x125) - $750 net (limited availability)

DAC E-Daily - 35,000 Subscribers
Leverage Chip Design's DAC coverage by positioning your advertising in our special e-Show Daily e-Newsletter and on ChipDesignMag.com distributed daily during DAC (June 8-10). The daily newsletter goes out to over 35,000 subscribers.

Platinum	$2,500
Gold	$2,000
Silver #1	$1,000
Silver #2	$1,000
Silver #3	$1,000

▶ Chip Design Premium Content Channel

Create valuable content featuring your company and technology and deliver it to your target audience through the entire Chip Design Network

To learn more how you company can sponsor the Chip Design Premium Content Channel, Contact Gabe Moretti at **gmoretti@extendionmedia.com**

2016 Editorial Calendar

	MAGAZINE		FOCUS REPORTS	MARKET RESEARCH	E-NEWSLETTERS				
	Magazine Topics	Bonus Distribution		Lead Generation	Chip Designer	IP Designer & Integration	FPGA & PLD Quarterly Report	Sensors & MEMs Quarterly Report	RF & Microwave Systems Qrtly.
WINTER/SPRING ISSUE	**Ad Close: Jan 14 Material: Jan 16** Semiconductor HW-SW CoDesign Processors Low Power IP Modeling	DesignCon (Santa Clara, CA) Embedded World (Nuremburg, Germany) DV Con 2016 (San Jose, CA) DATE (Dresden, Germany)		**IP Integration EDA Tech & Tools**	Jan. 14, 28 Feb. 10, 24 Mar. 16, 30 Apr. 13, 27 May 10, 25	Jan. 21 Feb. 17 Mar. 23 Apr. 20 May 18	Feb. 11 May 19	Jan. 14 April 14	Feb. 4 May 5
RF AND MICROWAVE SYSTEM	**Ad Close: April 6 Material: April 10** Wearable Electronics and RF/Microwave for IoT RF/Microwave IP Telecommunications RFID Packaging Considerations Testing Beyond 40 GHz	IMS 2016 DAC (San Francisco) Mobile World Congress 2017		**RF/Microwave Chip Design/ Test**	Special Issue Sponsored by IMS 2016				
SUMMER/FALL ISSUE	**Ad Close: May 14 Material: May 16** Designing Sub-10nm ICs Design Troubleshooting: Analysis and Debugging Tools Design Automation for the IoT Chip-Package-Board Co-Design Power, Performance, Area (PPA) Optimization Understanding Giga-Scale Challenges	DAC (San Francisco, CA) Semicon West (San Francisco, CA) Digital Only	Annual Resource Guide	**Verification EDA Tech & Tools Webcast** Chip Design for the Internet of Things	June 15, 29 July 13, 27 Aug. 17, 31 Sept. 14, 28 Oct. 12, 26 Nov. 10	June 22 July 21 Aug. 18 Sept. 22 Oct. 20 Nov. 17	Aug. 18 Nov. 10	July 14 Oct. 13	Aug. 4 Nov. 3
WINTER/SPRING ISSUE	**Ad Close: Dec 5 Material: Dec 10** Design for Automotive System Level Design Power Management Virtual Prototyping IP Selection, Reuse How to Design for 3D Integration	DesignCon 2017 (Santa Clara, CA) Embedded World DVCon DATE			Nov. 30 Dec. 7, 14	Dec. 15			Feb. 3, 2016